# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]

- Compaq Q2010s LCD Monitor
- Name / Model #2
- Name / Model #3
- Name / Model #4
- Name / Model #5

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>2</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>3</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. External Electric Cables Dissecting Process
2. Remove Stand Base From Display
3. Remove Front Cover From Display Head
4. Remove Rear Cover From Display Head
5. Remove Mainframe & Panel
6. Take Screw off From Power Bd & Main Bd & Remove Mainframe
7. Remove Stand & Base
8. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP Q2010s Disassembly Process

Xu Lei
Nov-10-09
External Electric Cables Dissecting Process

1. Remove Cable From Display Head.
2. Dissecting To Complete.

Power Cable
Remove Stand Base From Display

1. Remove Hinge Cover.

2. Take Screw(*4) From Stand.
Remove Front & Rear Cover From Display Head


2. Remove Front Cover.
1. Remove Speaker.

2. Remove KEPC Board.

Remove Connector off from the speaker

Remove Connector off from the KEPC board
Remove Front & Rear Cover From Display Head

1. Remove the Rear Cover.
1. Remove connector off from Panel.
Remove Mainframe & Panel

1. Take Screw(*2) From Mainframe.

2. Remove Connector off from Power board.

3. Remove connector off from Panel.

4. Remove the panel.
Take Screw off From Power Bd & Main Bd
& Remove Mainframe

1. Remove the Tape from the Mainframe.

2. Remove the KEPC from the Mainframe.

3. Take Screw(*2) From Mainframe.

4. Take Screw(*4) From Mainframe.
Take Screw off From Power Bd & Main Bd
& Remove Mainframe

1. Take screw(4) off from Powerboard.
2. Take screw(1) off from Mainboard.
3. Take Mainboard off from Mainframe.
4. Take Powerboard off from Mainframe.
Take Screw off From Power Bd & Main Bd & Remove Mainframe

3. Remove connector off from PCB board.
1. Remove Stand from the Base.

2. Take screw(*4) off from Hinge.